

Product Specification

Product:	Silver-Platinum Paste/ Ag Pt Paste (Pt1%)
Part Number:	03H-1801

Application Scope :

This product is suitable for use in thick-film circuits and sensor electrodes.

Usage Conditions :

Substrate	Alumina ceramics
Printing	200-300 mesh screen printing
Leveling	Let it level at room temperature for 5-15 minutes (adjust time based on actual leveling conditions).
Drying & Sintering	Furnace drying at 100-150°C for 10-15 minutes The sintering temperature is 850°C (recommended value) and the sintering time is 10 minutes.
Thinner	ST-1000

Characteristics :

1. Paste Characteristics :

Characteristic	Standard	Test Method And Conditions
1 Fineness	≤5μm	FOG test
2 Viscosity	130-280Pa.s	Brookfield HBT (Boli Fei) viscometer, rotor SC4-14/6R, operating at 10 rpm, with viscosity adjustable to 25±1°C according to user requirements.

2. Characteristics After Curing :

Under the 1-sintering condition, the film thickness is 8-12 μm.

Check fired film produced under the conditions specified in 1) , (Film thickness is 8-12μm.)

Characteristics	Standard	Test Method And Conditions
3 Resistivity	≤8mΩ/□	Test pattern 0.6mm×60mm

4	Adhesion Strength		Peel Test: 0.5mmφ Tin plated Cu wire soldered on 2mm×2mm Pad. Solder: 96.5Sn/0.5Cu Mildly activated flux used.
	Initial Adhesion	≥46.5N	
	Ageing Adhesion	≥26.3N	Aging conditions: 150°C, 24 hours

Save Conditions And Validity Period :

The product shall be stored in a sealed container at an ambient temperature of 5-25°C, with a shelf life of 1 year from the date of shipment.

Packaging Method :

Standard packaging, 1000g/can; samples are available in 200g small can packaging.